

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Borden, et al.

Assignee: Boxer Cross, Inc.

Title: IDENTIFYING DEFECTS IN A CONDUCTIVE STRUCTURE OF A
WAFER, BASED ON HEAT TRANSFER THERETHROUGH

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BOX Patent Application
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PRELIMINARY AMENDMENT

Dear Sir:

✓ Please amend the above-identified patent application as follows (a version with
markings to show changes made appears at the end):

IN THE CLAIMS

1. (Unchanged) A method of identifying a defect in a
semiconductor wafer, the method comprising:

applying heat to a conductive structure formed on said
semiconductor wafer;

measuring a signal indicative of temperature of a portion
of the conductive structure heated by conduction of the
applied heat therethrough, thereby to obtain a measurement;

repeating the act of measuring at each of a number of
different locations on the conductive structure, thereby to
obtain a plurality of measurements; and

determining presence of the defect in the conductive
structure, depending on the plurality of measurements.

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